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<b>(54) Title:</b> <u>A METHOD OF METALLIZING THE SURFACE OF A SOLID POLYMER SUBSTRATE AND THE PRODUCT OBTAINED</u>		
<b>(57) Abstract</b> <p>A method of metallizing a solid polymer substrate comprising the steps of: a) generating radicals on the substrate surface by subjecting it to a gas plasma, b) forming a layer on the surface using a plasma enhanced polymerisation process employing one or more monomers comprising monomers selected among cyano acrylate, mono- and diacrylates, such as acrylic acid, triethylen glycol diacrylate, glycidyl acrylate, isocyanates, such as 1,4-diisocyanobutane, toluenediisocyanate, epoxy compounds, such as glycidyl methacrylate, preferably 2,3-epoxypropyl methacrylate, allylic and vinylic compounds, such as vinyl acetic acid, vinyl norbonene, vinyl pyrrolidone, vinyl trimethoxysilane, vinyl trimethylsilane allylene, allyl alcohol, allyloxymethylsilane, allylphenol, allylurea 1-allylthiourea(thiosineamine), c) providing a short surface deposition using a PVD or CVD process to deposit metal atoms, such as copper, tin, silver palladium, platinum, or gold, and d) optionally providing a metallization of the surface by using a conventional electroless bath, or avoiding electroless metallization by using direct electrolytic metallization, when the metal layer formed in c) has a thickness allowing electrolytic metallization.</p>		